

03-07-2002

ASSIG



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R SHEET

WREN 3/4/2

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)  
a) Inderjit SINGH
2. Name and address of receiving party(ies):  
a) Name: National Semiconductor Corporation  
Address: 2900 Semiconductor Drive  
Santa Clara, CA 95052

3. Nature of conveyance  
☐ Assignment  
☐ Security Agreement  
☒ Other: Correction of State of Incorporation  
of Assignment recorded at Reel 8359 and  
Frame 0382 on 01/15/1997  
☐ Merger  
☐ Change of Name  
☐ License Agreement

Execution Date: January 15, 1997

4. Application Number(s) or Patent Number(s): 6,065,667

The title of the (new) application is:

**METHOD AND APPARATUS FOR FINE PITCH WIRE BONDING**

5. Please send all correspondence concerning this (these) documents to:

**Customer Number: 022434**


6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- ☒ Enclosed  
☒ Any additional fees are authorized to be charged to Deposit Account No. 500388  
(Order No. NSC1P087)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: February 28, 2002

  
Steve D Beyer  
Registration No. 31,234

03/06/2002 TDI A21 00000144 6065667

01 FC:581

40.00 DP

Attorney Docket No. NSC1P087

(Revised 01/96)

**PATENT**  
**REEL: 012631 FRAME: 0025**

02-25-1997



100352686

08784271  
01/15/97

**ASSIGNMENT RECORDATION COVER SHEET  
-PATENTS ONLY-**

To: Honorable Commissioner of Patents and Trademarks:

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1. Name of conveying party(ies)  
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3. Nature of conveyance  
☒ Assignment  
Security Agreement  
Other \_\_\_\_\_

Merger  
Change of Name

Execution Date: January 13, 1997

4. Application Number(s) or Patent Number(s):

The title of the (new) application is:

**METHOD AND APPARATUS FOR FINE PITCH WIRE BONDING**

5. Please send all correspondence concerning this (these) documents to:

Steve D Beyer  
HICKMAN BEYER & WEAVER  
P.O. Box 61059  
Palo Alto, CA 94306  
Tel. No.: (415) 493-6400  
Fax No.: (415) 493-6484

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

☒ Enclosed  
Authorized to be charged to Deposit Account No. 08-2120  
(Order No. \_\_\_\_\_)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: January 15, 1997

Steve D Beyer  
Registration No. 31,234

Attorney Docket No. NS3463/NSC1P087

(Revised 01/96)

**PATENT**  
**REEL: 012631 FRAME: 0026**

# ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set for in the patent application entitled:

## METHOD AND APPARATUS FOR FINE PITCH WIRE BONDING

(Atty. Docket No.: NSC1P087) for which I (we) have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/We the undersigned inventor(s) hereby:

1) Sell(s), assign(s) and transfer(s) to **National Semiconductor Corporation**, a California corporation having a place of business at 2900 Semiconductor Drive, Santa Clara, California, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.

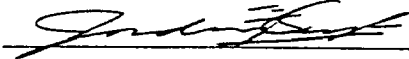
2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.

3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.

4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.

5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

1) Signature:  Date: 1/13/97  
Typed Name: Inderjit Singh

On this \_\_\_\_ day of \_\_\_\_\_, in the year 1997, before me, \_\_\_\_\_, personally appeared Inderjit Singh, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged to me that he/she executed the same in his/her authorized capacity(ies), and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Signature \_\_\_\_\_

(SEAL)

# ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

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WITNESS my hand and official seal.

Signature \_\_\_\_\_

(SEAL)